

ABSTRACT OF THE DISCLOSURE

A holder driving mechanism holds a wafer holder  
with gripping portions, and swings it within a wafer  
5 processing bath. When the peripheral portion of a wafer  
comes into contact with the distal end portion of a  
swing support member, the wafer rotates and vertically  
moves in the wafer holder. The wafer can be efficiently  
swung, and processing can be made uniform. By supplying  
10 ultrasonic waves from an ultrasonic bath, the processing  
rate can be increased.